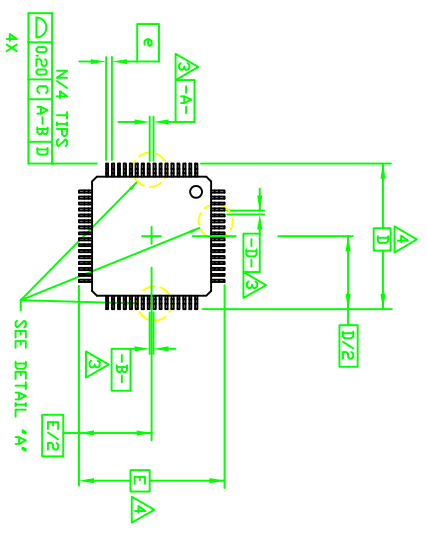
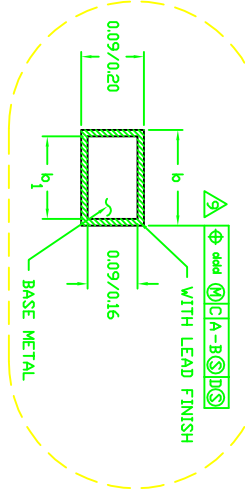
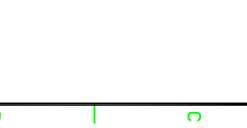
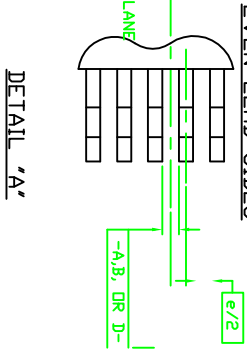
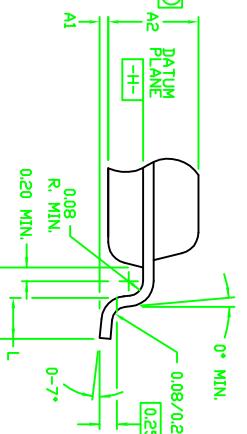
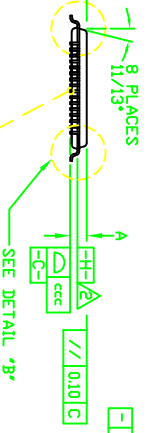
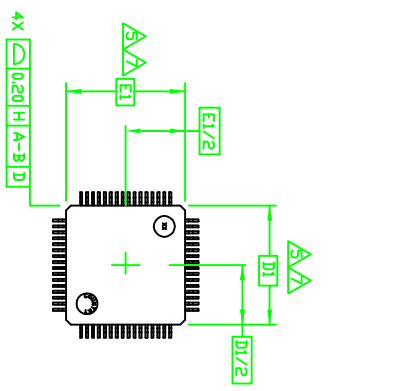


REV	DESCRIPTION	DATE	REVISION
00	INITIAL RELEASE PER DGN #A96560.	09/97	Y.M.K.
01	INC. PER DGN #D20884.	08/97	Y.M.K.
02	REVISED PER DGN #D21719. (ENG-AE-941 BECOMES 34604/02)	08/98	Y.M.K.
03	REVISED PER DGN #D21963.	08/98	Y.M.K.
04	REVISED PER DGN #D22151.	08/98	Y.M.K.
05	REVISED PER DGN #D24557.	07/98	M.P.
06	REVISED PER DGN #D25661	05/98	M.P.

TOP VIEW



BOTTOM VIEW



DECIMAL ANGULAR ±

XXX±  
XXXX±  
XXXX±

PRODUCTION APPROVALS DATE TITLE  
 APPROVALS IQ PARK 08/97  
 CK PARK 08/97  
 SH AHN 08/97  
 YM KANG 08/97

Author: Industrial Co. Ltd. Author: Electronics Inc.  
 1980 S. FRENCH RD. 1980 S. FRENCH RD.  
 SUITE 200, HOUSTON, TEXAS 77058 SUITE 200, HOUSTON, TEXAS 77058  
 Excellence in semiconductor assembly Excellence in semiconductor assembly  
 gnm gnm  
 PACKAGE OUTLINE, LQFP, 7 X 7 MM BODY,  
 100/010 MM FORM, 1.40 MM THICK

SIZE 7x7mm  
 A1  
 SCALE 6/1  
 SHEET 1 OF 2  
 REV. 06